

Part Number: **B0530W-7-F, B0540W-7-F, B0520LW-7-F**  
Weight (mg): 10.655

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Die,Schottky	Doped silicon	Doped silicon *	7440-21-3	100.00%	3.447	0.367	1000000	34469
SOD-123 leadframe	Alloy 42	Fe	7439-89-6	57.65%	28.111	2.995	576500	162062
		Ni	7440-02-0	41.00%			410000	115256
		Mn	7439-96-5	0.60%			6000	1687
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	281
		Co	7440-48-4	0.50%			5000	1406
		Si	7440-21-3	0.15%			1500	422
	Pure silver	Ag	7440-22-4	100.00%	0.853	0.091	1000000	8530
Bonding wire	1.4mil	Au	7440-57-5	100.00%	0.512	0.055	1000000	5122
Molding compound	KTMC-1050G	SiO2	60676-86-0	69.00%	64.041	6.824	690000	441884
		Epoxy Resin	29690-82-2	14.00%			140000	89658
		Phenol Resin	9003-35-4	7.00%			70000	44829
		Mg(OH)2	1309-42-8	8.00%			80000	51233
		C	1333-86-4	0.20%			2000	1281
		others	----	1.80%			18000	11527
Die attached epoxy	9005SP	Ag	7440-22-4	80.00%	1.032	0.110	800000	8256
		Bisphenol F	28064-14-4	15.00%			150000	1548
		Glycidyl neodeconate	26761-45-5	5.00%			50000	516
Tin solder	Pure Tin	Sn	7440-31-5	100.00%	2.003	0.213	1000000	20035
					100.00	10.655		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

\* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Antimony compounds	Organic tin compounds
Asbestos	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including <b>DecaBDE</b>
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Halogens	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Hexavalent chromium compounds	Radioactive Substances
Lead and lead compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Mercury and mercury compounds	Tributyl Tin Oxide (TBTO)

This product or product family does not contain any chemicals designated by the European Chemicals Agency (ECHA) as Substances of Very High Concern (SVHCs) under REACH. Please check the document at [http://www.diodes.com/files/products\\_lead\\_free/RoHS\\_Product\\_List.pdf](http://www.diodes.com/files/products_lead_free/RoHS_Product_List.pdf) for the current compliance status.